

## General Description

The MY2305 is the high cell density trenched P-CH MOSFET, which provide excellent  $R_{DS(ON)}$  and efficiency for most of the small power switching and load switch applications.

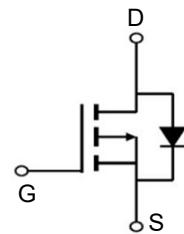
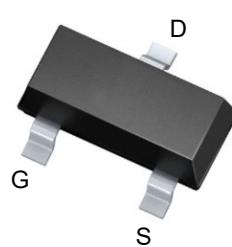


## Features

|   |      |           |
|---|------|-----------|
| $V_{DSS}$                               | -20  | V         |
| $I_D$                                   | -4.2 | A         |
| $R_{DS(ON)}(\text{at } V_{GS} = -4.5V)$ | 35   | $m\Omega$ |
| $R_{DS(ON)}(\text{at } V_{GS} = -2.5V)$ | 39   | $m\Omega$ |

## Application

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline



## Package Marking and Ordering Information

| Product ID | Pack   | Marking | Qty(PCS) |
|------------|--------|---------|----------|
| MY2305     | SOT-23 | 2305    | 3000     |

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

| Symbol                 | Parameter                                    | Rating     | Units      |
|------------------------|--|------------|------------|
| $V_{DS}$               | Drain-Source Voltage                         | -20        | V          |
| $V_{GS}$               | Gate-Source Voltage                          | $\pm 12$   | V          |
| $I_D @ T_A=25^\circ C$ | Continuous Drain Current, $V_{GS} @ -4.5V^1$ | -4.2       | A          |
| $I_D @ T_A=70^\circ C$ | Continuous Drain Current, $V_{GS} @ -4.5V^1$ | -3.0       | A          |
| $I_{DM}$               | Pulsed Drain Current <sup>2</sup>            | -16        | A          |
| $P_D @ T_A=25^\circ C$ | Total Power Dissipation <sup>3</sup>         | 1.31       | W          |
| $P_D @ T_A=70^\circ C$ | Total Power Dissipation <sup>3</sup>         | 0.84       | W          |
| $T_{STG}$              | Storage Temperature Range                    | -55 to 150 | $^\circ C$ |
| $T_J$                  | Operating Junction Temperature Range         | -55 to 150 | $^\circ C$ |

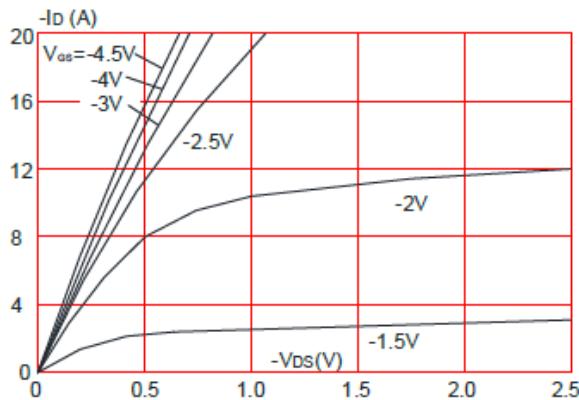
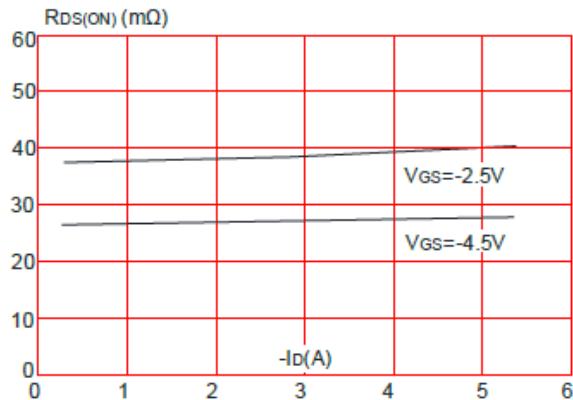
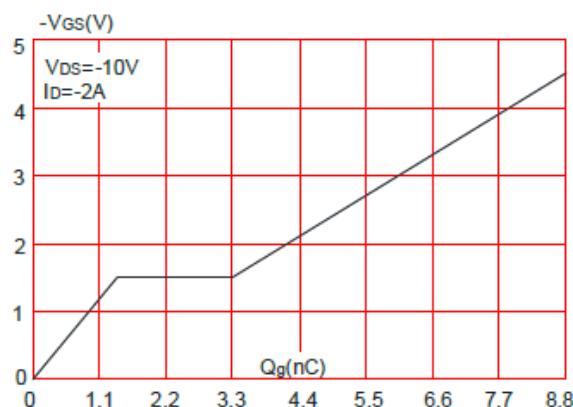
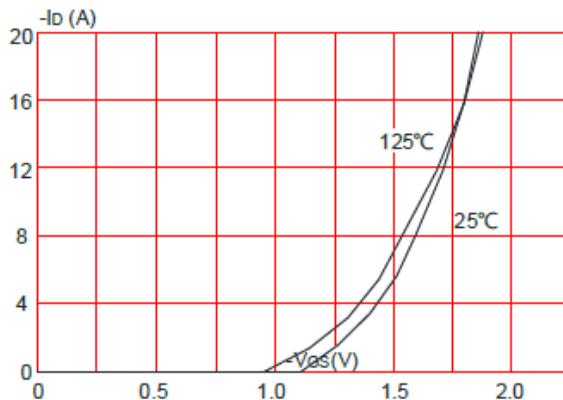
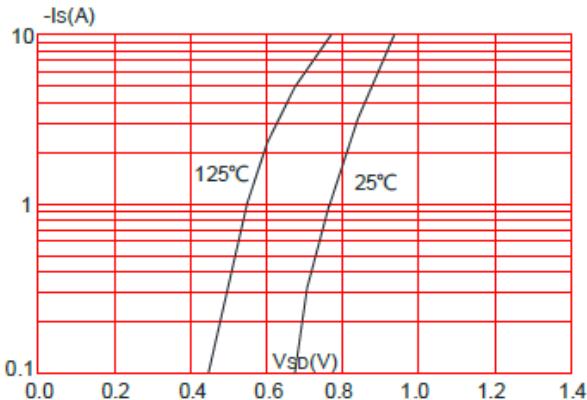
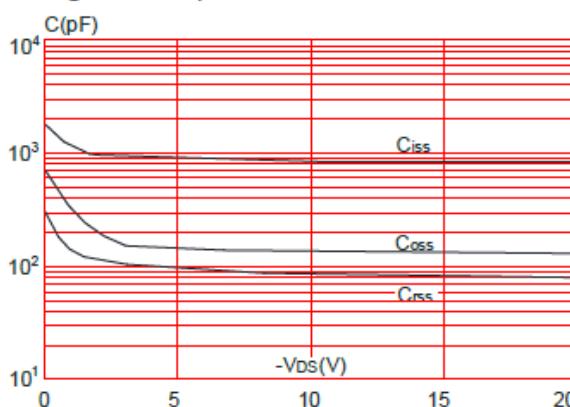
**Electrical Characteristics (T<sub>j</sub>=25 °C, unless otherwise noted)**

| Symbol  | Parameter  | Test Condition   | Min. | Typ. | Max. | Units |
|---|--|--|------|------|------|-------|
| <b>Off Characteristics</b>                                    |  |  |      |      |      |       |
| V <sub>(BR)DSS</sub>  | Drain-Source Breakdown Voltage                           | V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA   | -20  | -    | -    | V     |
| I <sub>DSS</sub>  | Zero Gate Voltage Drain Current                          | V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V,   | -    | -    | -1   | μA    |
| I <sub>GSS</sub>  | Gate to Body Leakage Current                             | V <sub>DS</sub> =0V, V <sub>GS</sub> = ±12V  | -    | -    | ±100 | nA    |
| <b>On Characteristics</b>                                     |  |  |      |      |      |       |
| V <sub>GS(th)</sub>   | Gate Threshold Voltage                                   | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA                                       | -0.4 | -0.7 | -1.0 | V     |
| R <sub>DS(on)</sub><br>note2                                  | Static Drain-Source on-Resistance                        | V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4.1A  | -    | 35   | 42   | mΩ    |
|   |  | V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -3A  | -    | 39   | 53   |       |
| <b>Dynamic Characteristics</b>                                |  |  |      |      |      |       |
| C <sub>iss</sub>  | Input Capacitance  | V <sub>DS</sub> = -10V, V <sub>GS</sub> =0V,<br>f=1.0MHz   | -    | 830  | -    | pF    |
| C <sub>oss</sub>  | Output Capacitance                                       |  | -    | 132  | -    | pF    |
| C <sub>rss</sub>  | Reverse Transfer Capacitance                             |  | -    | 85   | -    | pF    |
| Q <sub>g</sub>  | Total Gate Charge  | V <sub>DS</sub> = -10V, I <sub>D</sub> = -2A,<br>V <sub>GS</sub> = -4.5V                         | -    | 8.8  | -    | nC    |
| Q <sub>gs</sub>   | Gate-Source Charge                                       |  | -    | 1.4  | -    | nC    |
| Q <sub>gd</sub>   | Gate-Drain("Miller") Charge                              |  | -    | 1.9  | -    | nC    |
| <b>Switching Characteristics</b>                              |  |  |      |      |      |       |
| t <sub>d(on)</sub>  | Turn-on Delay Time                                       | V <sub>DD</sub> = -10V, I <sub>D</sub> = -3.3A,<br>R <sub>G</sub> = 1Ω, V <sub>GEN</sub> = -4.5V | -    | 10   | -    | ns    |
| t <sub>r</sub>  | Turn-on Rise Time  |  | -    | 32   | -    | ns    |
| t <sub>d(off)</sub>   | Turn-off Delay Time                                      |  | -    | 50   | -    | ns    |
| t <sub>f</sub>  | Turn-off Fall Time                                       |  | -    | 51   | -    | ns    |
| <b>Drain-Source Diode Characteristics and Maximum Ratings</b> |  |  |      |      |      |       |
| I <sub>S</sub>  | Maximum Continuous Drain to Source Diode Forward Current | -  | -    | -5.0 | -    | A     |
| I <sub>SM</sub>   | Maximum Pulsed Drain to Source Diode Forward Current     | -  | -    | -16  | -    | A     |
| V <sub>SD</sub>   | Drain to Source Diode Forward Voltage                    | V <sub>GS</sub> =0V, I <sub>S</sub> = -4.1A  | -    | -    | -1.2 | V     |

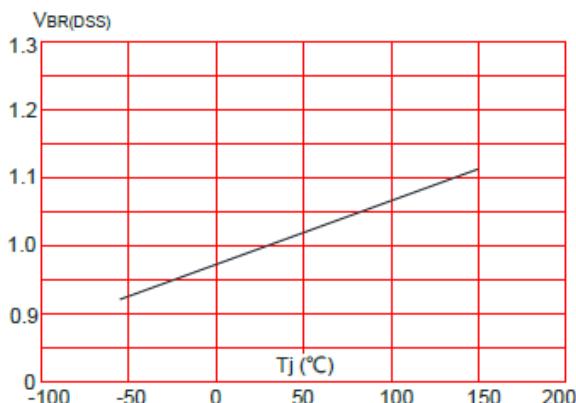
Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

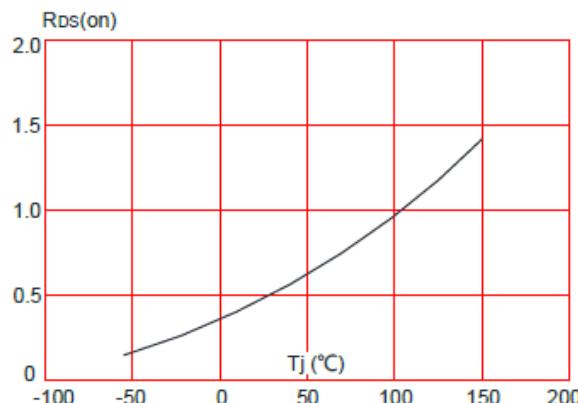
### Switching Time Test Circuit and Waveforms

**Figure 1:** Output Characteristics**Figure 3:** On-resistance vs. Drain Current**Figure 5:** Gate Charge Characteristics**Figure 2:** Typical Transfer Characteristics**Figure 4:** Body Diode Characteristics**Figure 6:** Capacitance Characteristics

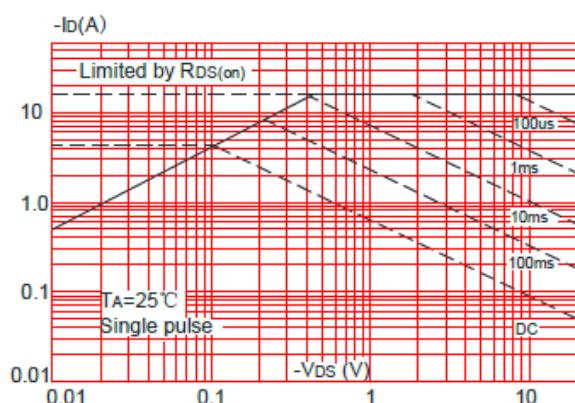
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



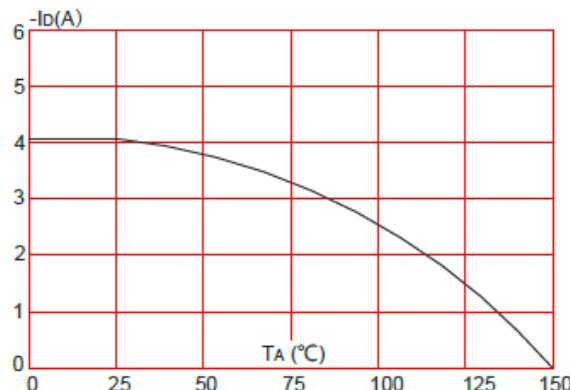
**Figure 8:** Normalized on Resistance vs. Junction Temperature



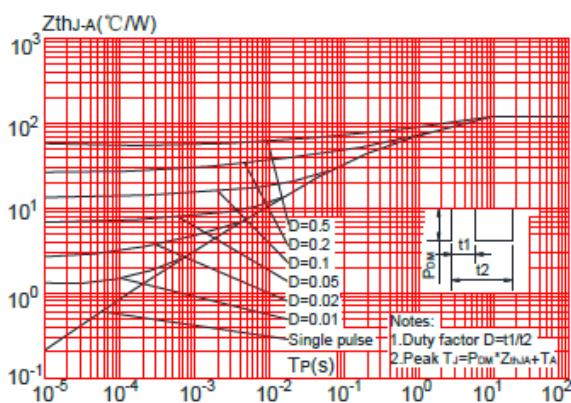
**Figure 9:** Maximum Safe Operating Area

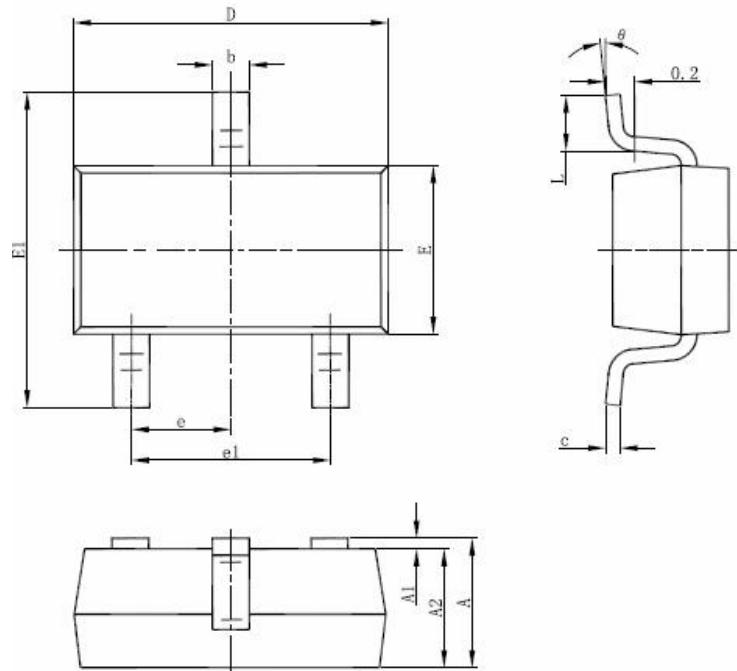


**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Package Mechanical Data-SOT-23**


| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.050                     | 1.250 | 0.041                | 0.049 |
| A1     | 0.000                     | 0.100 | 0.000                | 0.004 |
| A2     | 1.050                     | 1.150 | 0.041                | 0.045 |
| b      | 0.300                     | 0.500 | 0.012                | 0.020 |
| c      | 0.100                     | 0.200 | 0.004                | 0.008 |
| D      | 2.820                     | 3.020 | 0.111                | 0.119 |
| E      | 1.500                     | 1.700 | 0.059                | 0.067 |
| E1     | 2.650                     | 2.950 | 0.104                | 0.116 |
| e      | 0.950(BSC)                |       | 0.037(BSC)           |       |
| e1     | 1.800                     | 2.000 | 0.071                | 0.079 |
| L      | 0.300                     | 0.600 | 0.012                | 0.024 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |